

TECHNICAL REPORT



Circuit boards and circuit board assemblies – Design and use – Part 8: 3D shape data for CAD component library

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DESIGN AND USE –****Part 8: 3D shape data for CAD component library****FOREWORD**

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CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES – DESIGN AND USE –

Part 8: 3D shape data for CAD component library

1 Scope

This part of IEC 61188 describes the configuration of part shape data of semiconductor devices and electrical components registered in the CAD library.

This document mainly describes the configuration of 2D and 3D parts shape data.

2 Normative references

There are no normative references in this document.